

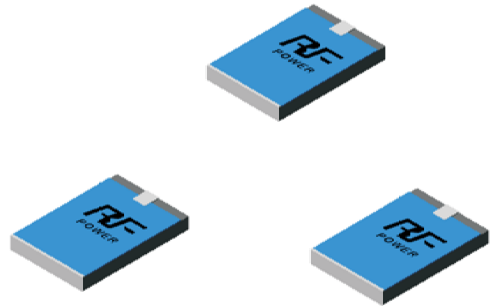
HIGH POWER CHIP TERMINATION

150W

When properly mounted on an appropriate heat sink, this chip device provides high power dissipation capabilities. Ideal for ferrite isolator applications, the improved thin film design technology and laser trimming provide proven RF power capabilities to meet the demands of today's CAMA and WCDMA system requirements.

- Environmentally friendly ALN substrate
- Hi-performance thin film element
- POWER HANDLING OF 150Watts
- New adhesion process results in improved terminal strength
- On-chip matching network improves frequency performance over the DC- 2 Ghz frequency range

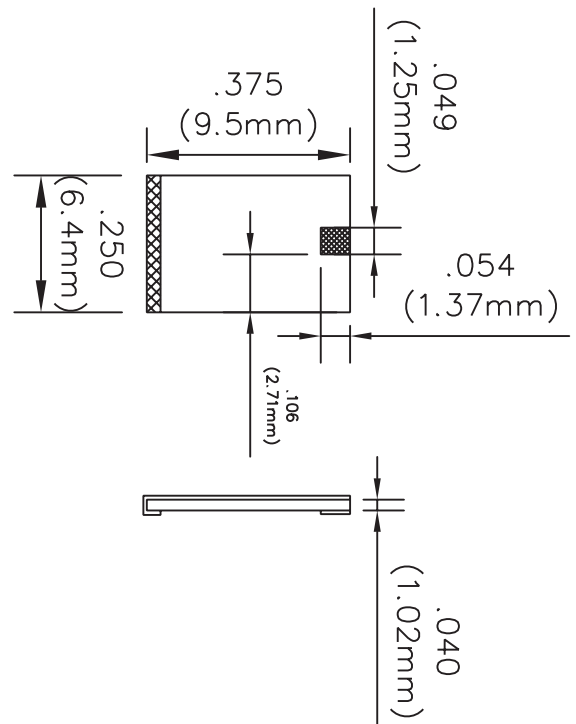
MANC250375T050G



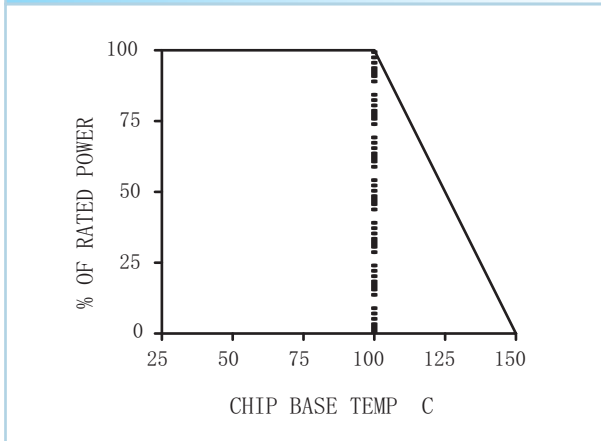
SPECIFICATIONS	
Parameters	Specifications
Frequency Range	DC to 2 Ghz
Power	150 Watts*
VSWR	1.25:1 max
Resistance	50 ohms +/- 5%
Operating Temperature	-55 C to 150 C
Substrate	Aluminum Nitride

* Refer to average power derating curve chart.

PHYSICAL DIMENSIONS



AVERAGE POWER DERATING CURVE



Ordering number:



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